



100% Material Declaration Data Sheet FG256

PK151 (v1.2) September 14, 2006

Material Declaration Data Sheet

Average Weight: 0.9408 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0749	7.97%
	Silicon	7440-21-3	100.00		0.0749	
Die Attach Material					0.0074	0.78%
	Silver	7440-22-4	78.00		0.0058	
	Resin	Trade Secret	22.00		0.0016	
Mold Compound					0.3748	39.84%
	Epoxy Resins	Trade Secret	12.00		0.0450	
	SiO2	60676-86-0	88.00	Filler	0.3298	
Laminate					0.2085	22.16%
	Laminate	Trade Secret	61.00		0.1272	
	Solder Mask	Trade Secret	17.36		0.0362	
	Copper	7440-50-8	16.00	Metal Layer	0.0334	
	Nickel	7440-02-0	4.80	Metal Layer	0.0100	
	Gold	7440-57-5	0.84	Metal Layer	0.0018	
Bond Wire					0.0043	0.46%
	Gold	7440-57-5	99.00		0.004263581	
	Silver	7440-22-4	0.0025		0.000000108	
	Copper	7440-50-8	0.0005		0.000000022	
	Iron	7439-89-6	0.0005		0.000000022	
	Calcium	7440-70-2	0.0020		0.000000086	
	Palladium	7440-05-3	0.9900		0.000042636	
	Magnesium	7439-95-4	0.0005		0.000000022	
Solder Balls					0.2709	28.79%
	Tin	7440-31-5	63.00		0.170667	
	Lead	7439-92-1	37.00		0.100233	

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
7/11/06	1.1	100% Material Declaration.
9/14/06	1.2	Deleted component description.